US00D425779S

United States Patent [19]

Nakamura

[11] **Patent Number: Des. 425,779**

[45] **Date of Patent: ** May 30, 2000**

[54] **WIRE BUNDLING SUPPORT**

[75] Inventor: **Toshinobu Nakamura**, Tokyo, Japan

[73] Assignee: **Shinagawa Shoko Co., Ltd.**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **29/107,184**

[22] Filed: **Jun. 29, 1999**

[51] **LOC (7) Cl.** **08-05**

[52] **U.S. Cl.** **D8/356**

[58] **Field of Search** .... D8/356; 24/16 PB; 248/68.1, 56, 74.4

[56] **References Cited**

U.S. PATENT DOCUMENTS

3,516,631	6/1970	Santucci	24/16 PB X
4,609,171	9/1986	Matsui	248/74.3

Primary Examiner—Holly Baynham
Attorney, Agent, or Firm—Frishauf, Holtz, Goodman, Langer & Chick, P.C.

[57] **CLAIM**

The ornamental design for a wire bundling support device, as shown and described.

DESCRIPTION

FIG. **1** is a front, top and left side perspective view of a wire bundling support showing my new design;

FIG. **2** is a front evevational view thereof, the rear elevational view being identical;

FIG. **3** is a top plan view thereof;

FIG. **4** is a bottom plan view thereof; and,

FIG. **5** is a left side view thereof, the right side view being a mirror image.

1 Claim, 2 Drawing Sheets

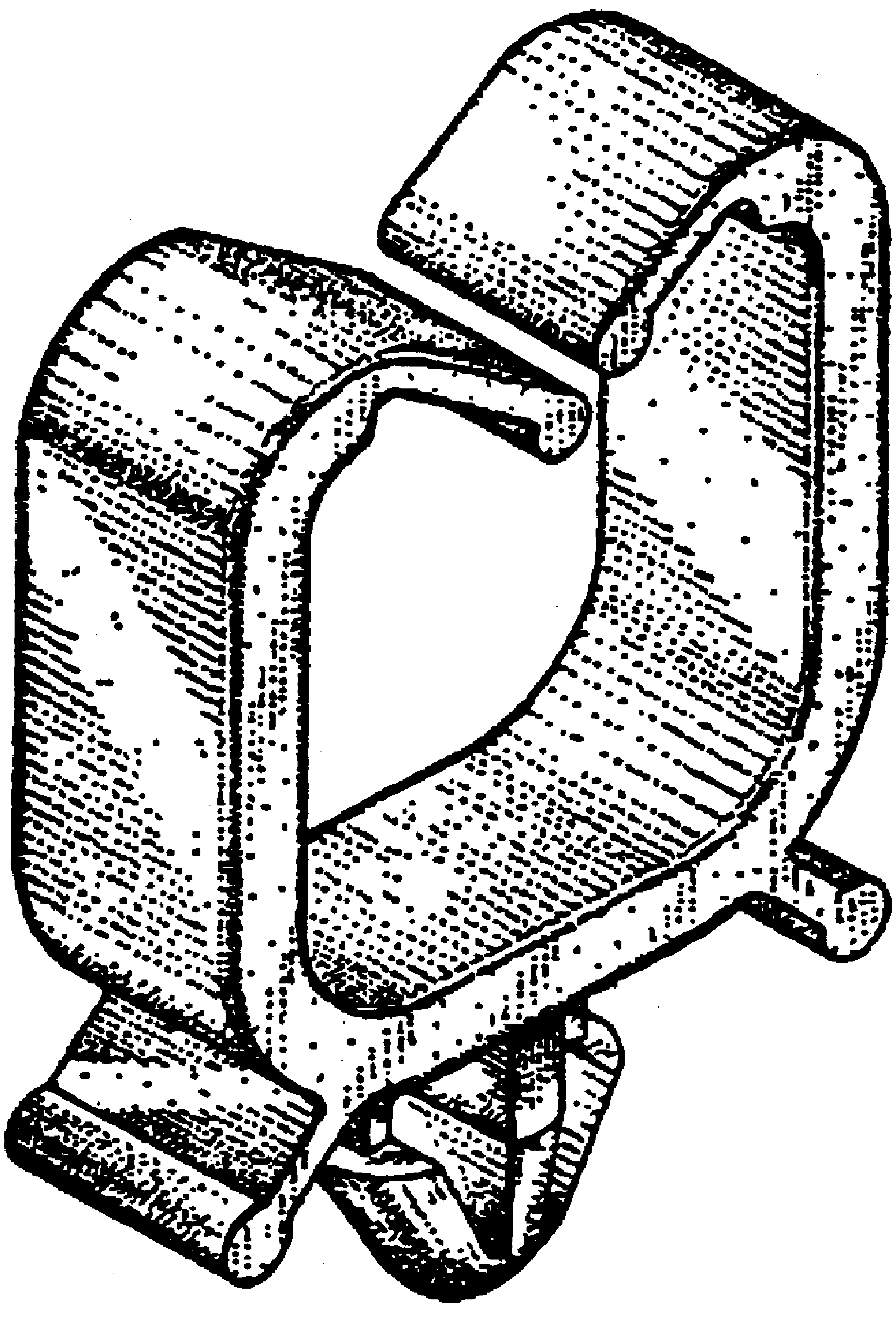

FIG.1

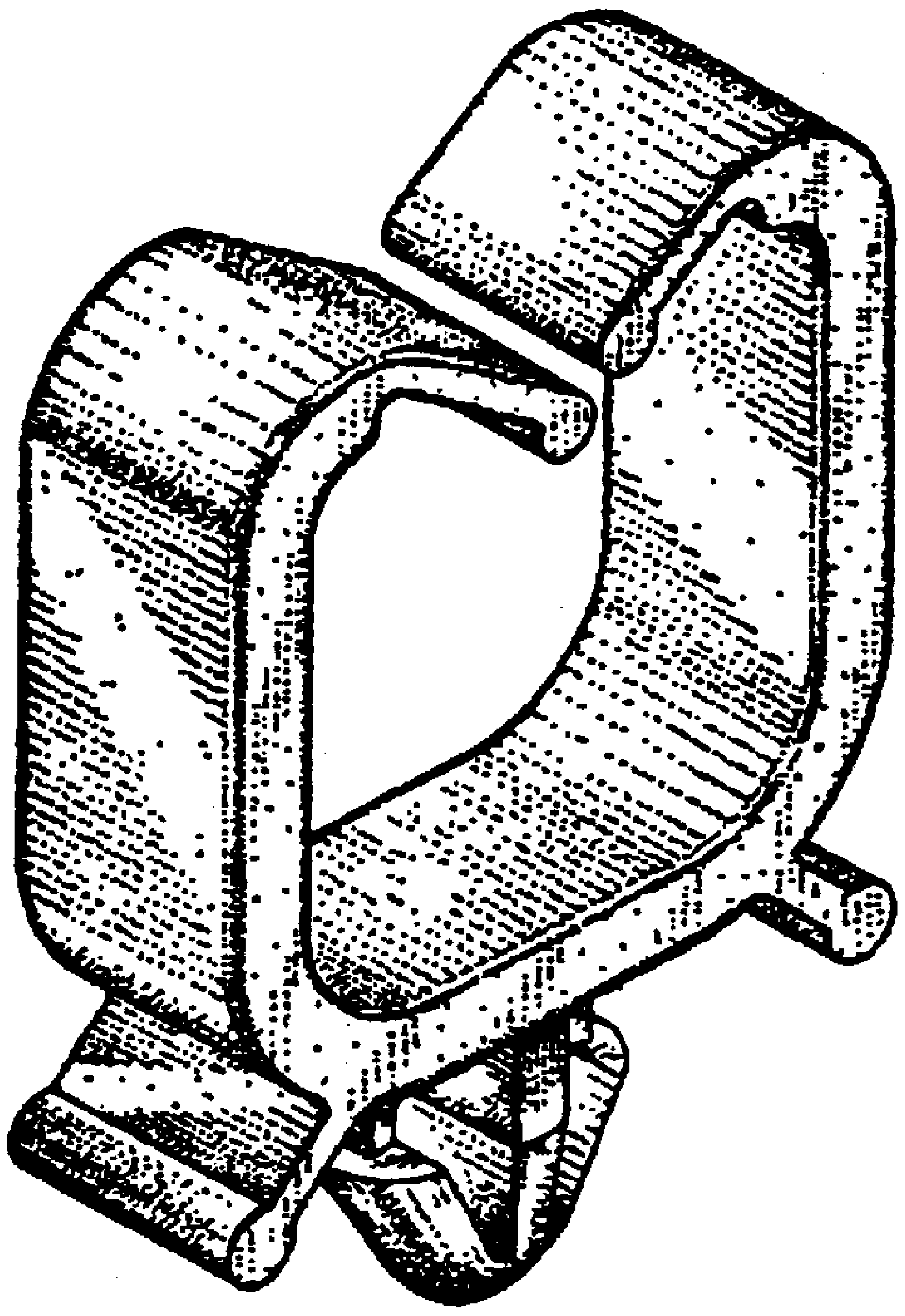

FIG.2

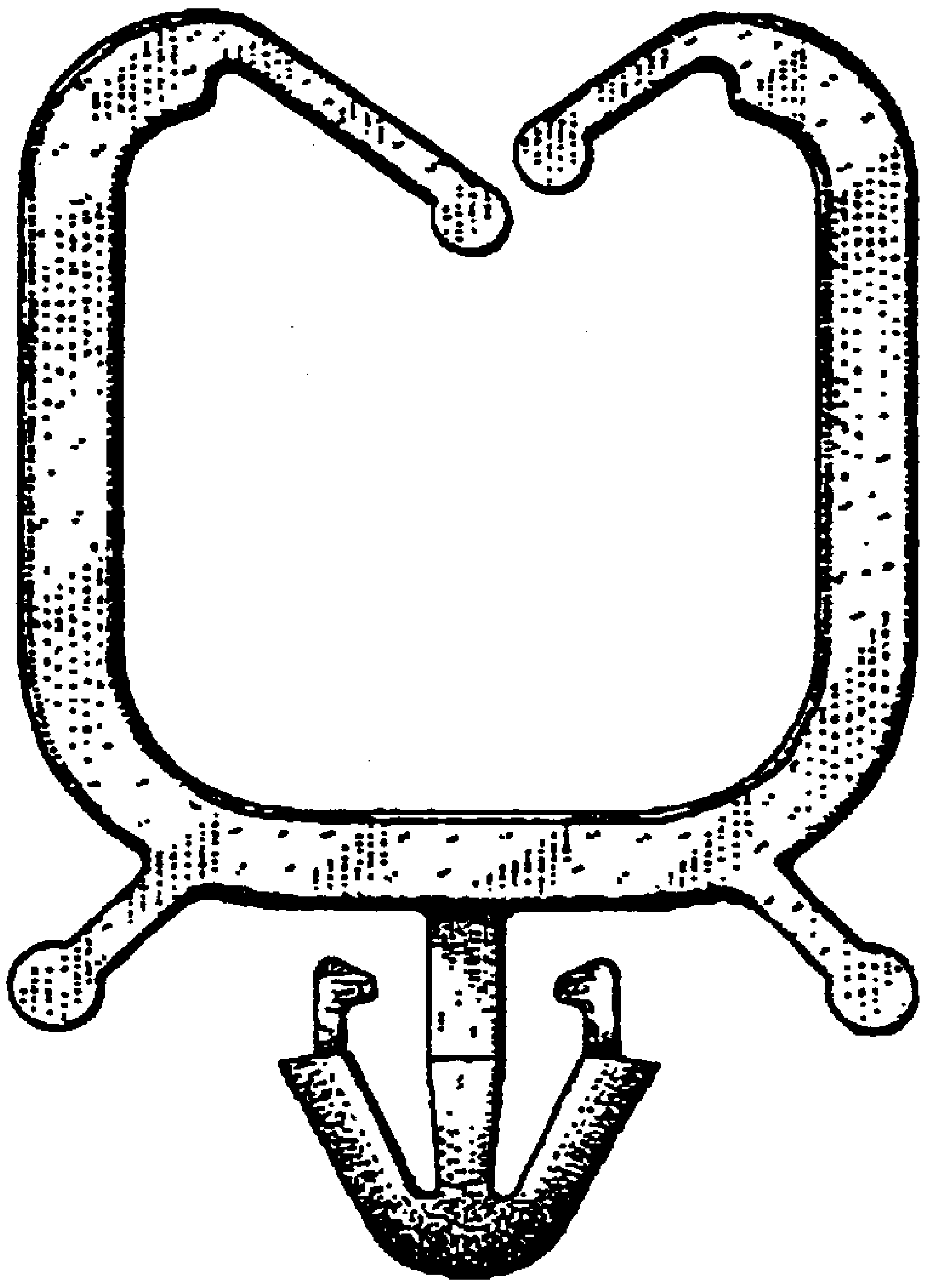

FIG.3

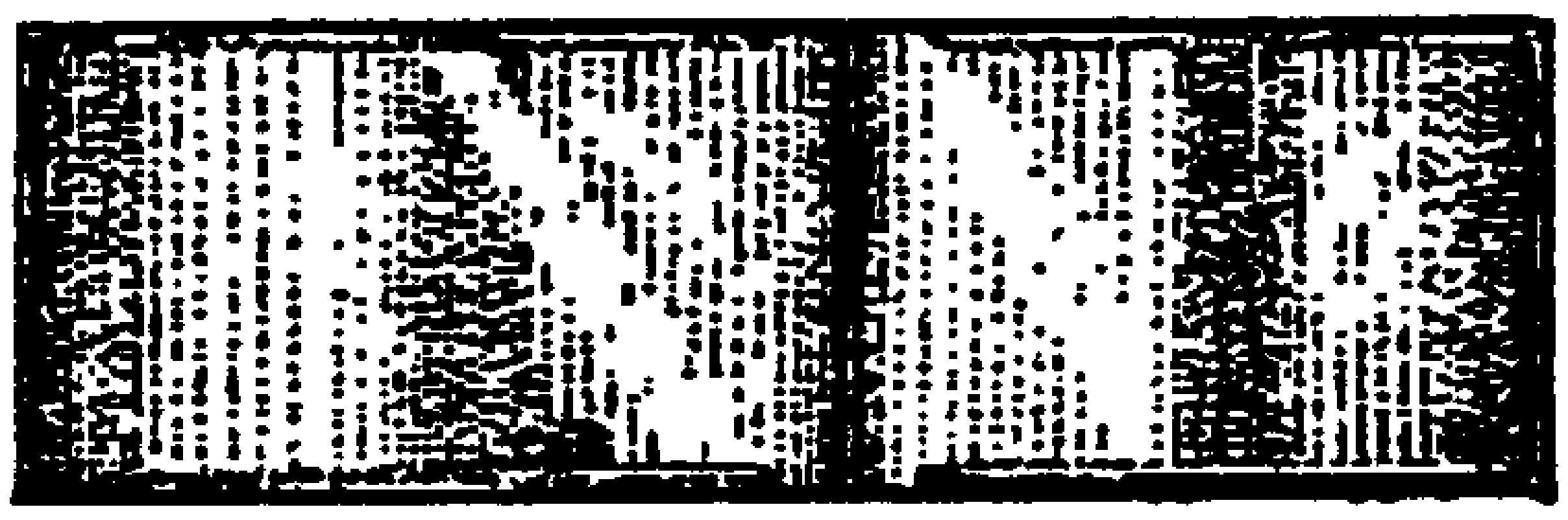

FIG.4

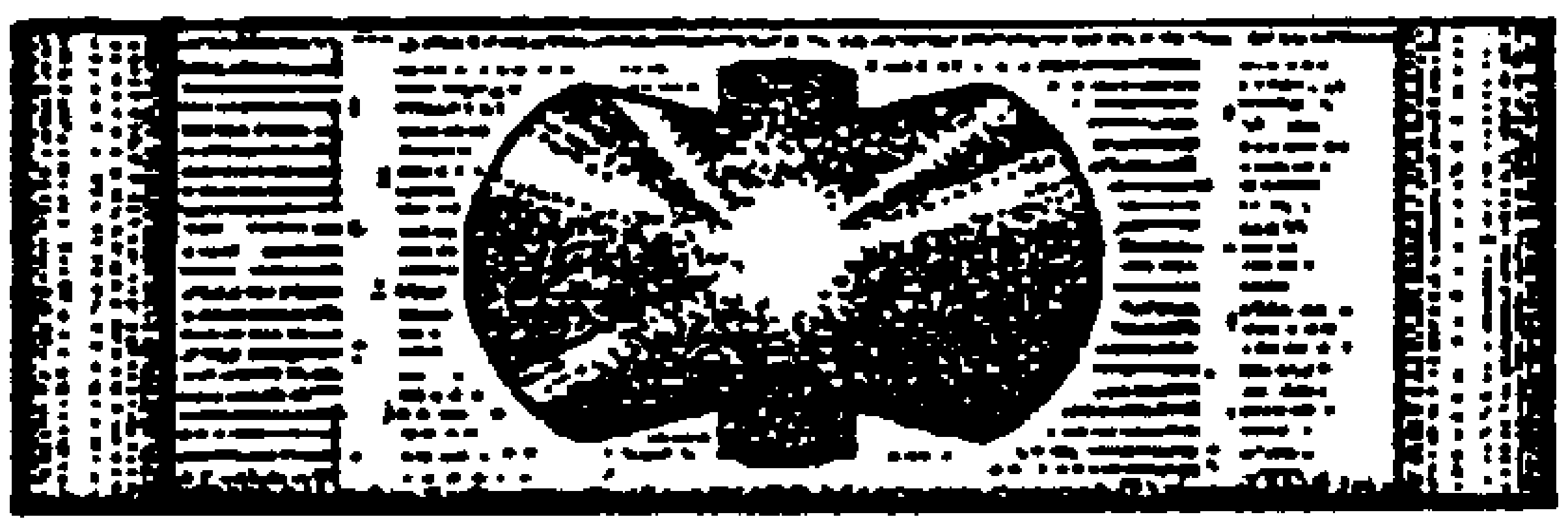

FIG.5